



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-02-03
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STS8DN6LF6AG	C207*7L62ACF	A	Z8GA	2017-02-03
Amount		UoM	Unit type	ST ECOPACK Grade
80.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	C207*7L62ACF					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	1.152	mg	supplier	die	Silicon (Si)	7440-21-3		1.098	mg	953125	13725
				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	12153	175
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1736	25
				supplier	Passivation	Silicon Nitride	12033-89-5		0.007	mg	6076	88
				supplier	Passivation	Silicon Oxide	7631-86-9		0.016	mg	13889	200
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	868	13
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.009	mg	7813	113
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.001	mg	868	13
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.004	mg	3472	50
				Leadframe	Copper & its alloys	32.009	mg	supplier	alloy	Copper(CU)	7440-50-8	
supplier	alloy	Iron(Fe)	7439-89-6						0.747	mg	23337	9338
supplier	alloy	Iron Phosphide(FeP)	26508-33-8						0.027	mg	843	338
supplier	alloy	Zinc(Zn)	7440-66-6						0.040	mg	1250	500
supplier	metallization	Silver(Ag)	7440-22-4						0.244	mg	7623	3050
Die attach	Other inorganic materials	0.335	mg	supplier	glue	Silver (Ag)	7440-22-4		0.291	mg	868657	3631
				supplier	glue	Bismaleimide resin	35325-39-4		0.021	mg	62687	263
				supplier	glue	isobornyl Methacrylate	7534-94-3		0.021	mg	62687	263
				supplier	glue	polymer	Proprietary		0.002	mg	5969	25
Bonding wire	Other inorganic materials	0.081	mg	supplier	wire	Copper (CU)	7440-50-8		0.081	mg	1000000	1013
Encapsulation	Other Organic Materials	42.540	mg	supplier	mold compound	Epoxy Resin	25068-38-6		3.193	mg	75059	39913
				supplier	mold compound	Phenol Resin	29690-82-2		2.128	mg	50024	26600
				supplier	mold compound	Silica, vitreous	60676-86-0		36.837	mg	865938	460463
				supplier	mold compound	Carbon black	1333-86-4		0.212	mg	4983	2650
Connections coating	Solder	3.883	mg	supplier	mold compound	Bismuth (Bi)	7440-69-9		0.170	mg	3996	2125
				supplier	solder alloy	Tin (Sn)	7440-31-5		3.883	mg	1000000	48538